Welcome to E-XFL.COM

Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	ARM920T
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	150MHz
Co-Processors/DSP	-
RAM Controllers	SDRAM
Graphics Acceleration	No
Display & Interface Controllers	LCD
Ethernet	-
SATA	-
USB	USB 1.x (1)
Voltage - I/O	1.8V, 3.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	256-LFBGA
Supplier Device Package	256-PBGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9328mxlvm15r2

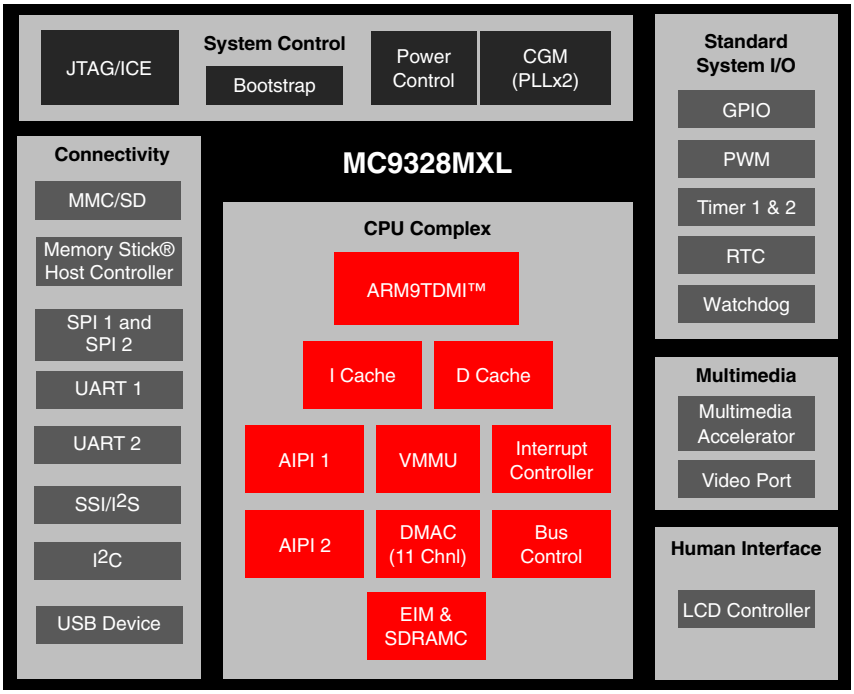


Figure 1. i.MXL Functional Block Diagram

1.1 Features

To support a wide variety of applications, the processor offers a robust array of features, including the following:

- ARM920T™ Microprocessor Core
- AHB to IP Bus Interfaces (AIPIs)
- External Interface Module (EIM)
- SDRAM Controller (SDRAMC)
- DPLL Clock and Power Control Module
- Two Universal Asynchronous Receiver/Transmitters (UART 1 and UART 2)
- Serial Peripheral Interface (SPI)
- Two General-Purpose 32-bit Counters/Timers
- Watchdog Timer
- Real-Time Clock/Sampling Timer (RTC)
- LCD Controller (LCDC)
- Pulse-Width Modulation (PWM) Module
- Universal Serial Bus (USB) Device
- Multimedia Card and Secure Digital (MMC/SD) Host Controller Module
- Memory Stick® Host Controller (MSHC)
- Direct Memory Access Controller (DMAC)
- Synchronous Serial Interface and an Inter-IC Sound (SSI/I^2S) Module
- Inter-IC (I^2C) Bus Module

Table 3. MC9328MXLMC9328MXS Signal Multiplexing Scheme (Continued)

I/O Supply Voltage	225 BGA Ball	256 BGA Ball	Primary			Alternate		GPIO		AIN	BIN	AOUT	Default
			Signal	Dir	Pull-Up	Signal	Dir	Mux	Pull-Up				
NVDD4	D8	F7	UART2_TXD	O				PB30	69K				PB30
NVDD4	E7	E7	$\overline{\text{UART2\_RTS}}$	I				PB29	69K				PB29
NVDD4	F7	C6	$\overline{\text{UART2\_CTS}}$	O				PB28	69K				PB28
NVDD4	B6	D7	USBD_VMO	O				PB27	69K				PB27
NVDD4	C6	D6	USBD_VPO	O				PB26	69K				PB26
NVDD4	A6	E6	USBD_VM	I				PB25	69K				PB25
NVDD4	D6	B6	USBD_VP	I				PB24	69K				PB24
NVDD4	A5	D5	USBD_SUSPND	O				PB23	69K				PB23
NVDD4	B5	C5	USBD_RCV	I/O				PB22	69K				PB22
NVDD4	A4	B5	$\overline{\text{USBD\_ROE}}$	O				PB21	69K				PB21
NVDD4	B4	A5	USBD_AFE	O				PB20	69K				PB20
NVDD4	A3	G7	PB19	I/O					69K				PB19
NVDD4	C4	F6	PB18	I/O					69K				PB18
NVDD4	D4	G6	PB17	O					69K				PB17
NVDD4	B3	B4	PB16	I					69K				PB16
NVDD4	A2	C4	PB15	I					69K				PB15
NVDD4	C3	D4	PB14	I					69K				PB14
NVDD4	A1	B3	SD_CMD	I/O		MS_BS		PB13	69K				PB13
NVDD4	B2	A3	SD_CLK	O		MS_SCLKO		PB12	69K				PB12
NVDD4	B1	A2	SD_DAT3	I/O		MS_SDIO		PB11	69K (pull down)				PB11
NVDD4	C5	E5	SD_DAT2	I/O		MS_SCLKI		PB10	69K				PB10
NVDD4	D3	B2	SD_DAT1	I/O		MS_PI1		PB9	69K				PB9
NVDD4	C2	C3	SD_DAT0	I/O		MS_PI0		PB8	69K				PB8
NVDD1	D5	K8	NVDD1	Static									
	G6	A1	NVSS	Static									
NVDD1	E5	H5	NVDD1	Static									
	H6	T1	NVSS	Static									
QVDD1	J8	H9	QVDD1	Static									
	E6	H8	QVSS	Static									

Table 5. Recommended Operating Range

Symbol	Rating	Minimum	Maximum	Unit
T_A	Operating temperature range MC9328MXLVM20/MC9328MXLVM15 MC9328MXLVP20/MC9328MXLVP15	0	70	°C
T_A	Operating temperature range MC9328MXLDVM20/MC9328MXLDVM15 MC9328MXLDVP20/MC9328MXLDVP15	-30	70	°C
T_A	Operating temperature range MC9328MXLCVM15/ MC9328MXLCVP15	-40	85	°C
NVDD	I/O supply voltage (if using MSHC, CSI, SPI, LCD, and USBd which are only 3 V interfaces)	2.70	3.30	V
NVDD	I/O supply voltage (if not using the peripherals listed above)	1.70	3.30	V
QVDD	Internal supply voltage (Core = 150 MHz)	1.70	1.90	V
QVDD	Internal supply voltage (Core = 200 MHz)	1.80	2.00	V
AVDD	Analog supply voltage	1.70	3.30	V

3.3 Power Sequence Requirements

For required power-up and power-down sequencing, please refer to the “Power-Up Sequence” section of application note AN2537 on the i.MX applications processor website.

3.4 DC Electrical Characteristics

Table 6 contains both maximum and minimum DC characteristics of the i.MXL processor.

Table 6. Maximum and Minimum DC Characteristics

Number or Symbol	Parameter	Min	Typical	Max	Unit
Iop	Full running operating current at 1.8V for QVDD, 3.3V for NVDD/AVDD (Core = 96 MHz, System = 96 MHz, MPEG4 decoding playback from external memory card to both external SSI audio decoder and driving TFT display panel, and OS with MMU enabled memory system is running on external SDRAM).	–	QVDD at 1.8V = 120mA; NVDD+AVDD at 3.0V = 30mA	–	mA
$Sidd_1$	Standby current (Core = 150 MHz, QVDD = 1.8V, temp = 25°C)	–	25	–	µA
$Sidd_2$	Standby current (Core = 150 MHz, QVDD = 1.8V, temp = 55°C)	–	45	–	µA
$Sidd_3$	Standby current (Core = 150 MHz, QVDD = 2.0V, temp = 25°C)	–	35	–	µA
$Sidd_4$	Standby current (Core = 150 MHz, QVDD = 2.0V, temp = 55°C)	–	60	–	µA

Table 6. Maximum and Minimum DC Characteristics (Continued)

Number or Symbol	Parameter	Min	Typical	Max	Unit
V_{IH}	Input high voltage	$0.7V_{DD}$	–	Vdd+0.2	V
V_{IL}	Input low voltage	–	–	0.4	V
V_{OH}	Output high voltage (I_{OH} = 2.0 mA)	$0.7V_{DD}$	–	Vdd	V
V_{OL}	Output low voltage (I_{OL} = -2.5 mA)	–	–	0.4	V
I_{IL}	Input low leakage current (V_{IN} = GND, no pull-up or pull-down)	–	–	±1	µA
I_{IH}	Input high leakage current (V_{IN} = V_{DD}, no pull-up or pull-down)	–	–	±1	µA
I_{OH}	Output high current (V_{OH} = $0.8V_{DD}$, V_{DD} = 1.8V)	4.0	–	–	mA
I_{OL}	Output low current (V_{OL} = 0.4V, V_{DD} = 1.8V)	-4.0	–	–	mA
I_{OZ}	Output leakage current (V_{out} = V_{DD}, output is high impedance)	–	–	±5	µA
C_i	Input capacitance	–	–	5	pF
C_o	Output capacitance	–	–	5	pF

3.5 AC Electrical Characteristics

The AC characteristics consist of output delays, input setup and hold times, and signal skew times. All signals are specified relative to an appropriate edge of other signals. All timing specifications are specified at a system operating frequency from 0 MHz to 96 MHz (core operating frequency 150 MHz) with an operating supply voltage from $V_{DD\ min}$ to $V_{DD\ max}$ under an operating temperature from T_L to T_H. All timing is measured at 30 pF loading.

Table 7. Tristate Signal Timing

Pin	Parameter	Minimum	Maximum	Unit
TRISTATE	Time from TRISTATE activate until I/O becomes Hi-Z	–	20.8	ns

Table 8. 32k/16M Oscillator Signal Timing

Parameter	Minimum	RMS	Maximum	Unit
EXTAL32k input jitter (peak to peak)	–	5	20	ns
EXTAL32k startup time	800	–	–	ms
EXTAL16M input jitter (peak to peak) [1]	–	TBD	TBD	–
EXTAL16M startup time [1]	TBD	–	–	–

[1] The 16 MHz oscillator is not recommended for use in new designs.

Table 11. Reset Module Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Min	Max	Min	Max	
1	Width of input POWER_ON_RESET	note[1]	–	note[1]	–	–
2	Width of internal $\overline{\text{POWER\_ON\_RESET}}$ (CLK32 at 32 kHz)	300	300	300	300	ms
3	7K to 32K-cycle stretcher for SDRAM reset	7	7	7	7	Cycles of CLK32
4	14K to 32K-cycle stretcher for internal system reset $\overline{\text{HRESERT}}$ and output reset at pin $\overline{\text{RESET\_OUT}}$	14	14	14	14	Cycles of CLK32
5	Width of external hard-reset $\overline{\text{RESET\_IN}}$	4	–	4	–	Cycles of CLK32
6	4K to 32K-cycle qualifier	4	4	4	4	Cycles of CLK32

[1] POR width is dependent on the 32 or 32.768 kHz crystal oscillator start-up time. Design margin should allow for crystal tolerance, i.MX chip variations, temperature impact, and supply voltage influence. Through the process of supplying crystals for use with CMOS oscillators, crystal manufacturers have developed a working knowledge of start-up time of their crystals. Typically, start-up times range from 400 ms to 1.2 seconds for this type of crystal.
If an external stable clock source (already running) is used instead of a crystal, the width of POR should be ignored in calculating timing for the start-up process.

4.4 External Interface Module

The External Interface Module (EIM) handles the interface to devices external to the i.MXL processor, including the generation of chip-selects for external peripherals and memory. The timing diagram for the EIM is shown in Figure 5, and Table 12 defines the parameters of signals.

4.4.2.1 WAIT Read Cycle without DMA

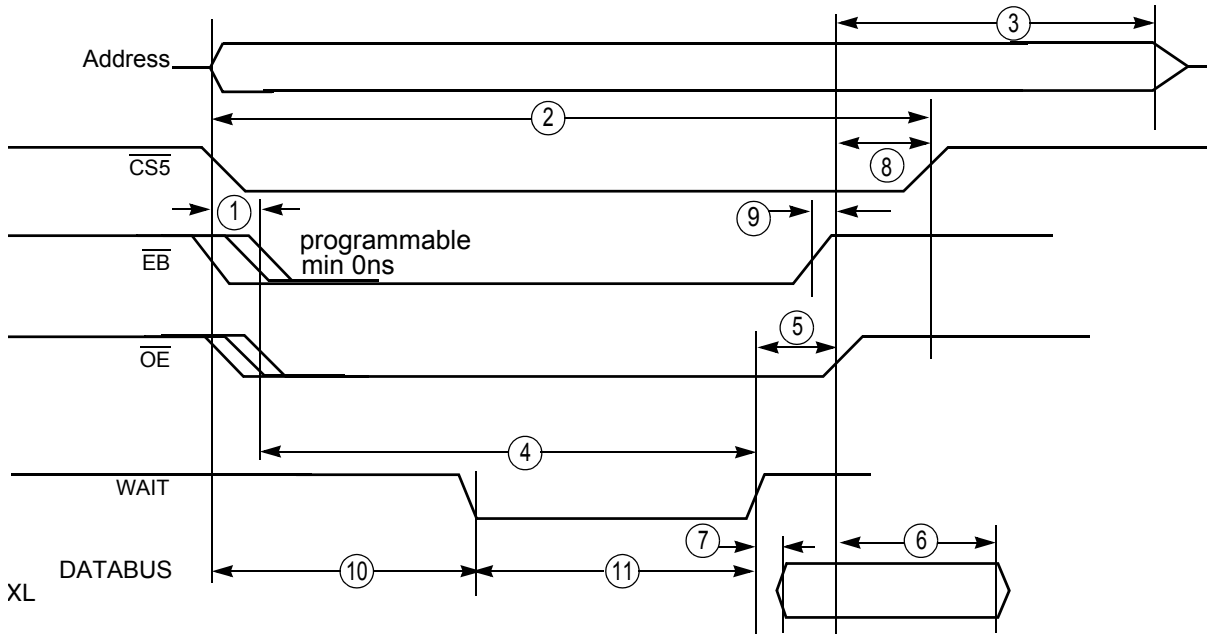


Figure 6. WAIT Read Cycle without DMA

Table 13. WAIT Read Cycle without DMA: WSC = 111111, DTACK_SEL=1, HCLK=96MHz

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{OE}$ and $\overline{EB}$ assertion time	See note 2	–	ns
2	$\overline{CS5}$ pulse width	3T	–	ns
3	$\overline{OE}$ negated to address inactive	56.81	57.28	ns
4	Wait asserted after $\overline{OE}$ asserted	–	1020T	ns
5	Wait asserted to $\overline{OE}$ negated	2T+1.57	3T+7.33	ns
6	Data hold timing after $\overline{OE}$ negated	T-1.49	–	ns
7	Data ready after wait asserted	0	T	ns
8	OE negated to CS negated	1.5T-0.68	1.5T-0.06	ns
9	OE negated after EB negated	0.06	0.18	ns
10	Become low after CS5 asserted	0	1019T	ns
11	Wait pulse width	1T	1020T	ns

Note:
1. T is the system clock period. (For 96 MHz system clock, T=10.42 ns)
2. $\overline{OE}$ and $\overline{EB}$ assertion time is programmable by OEA bit in CS5L register. $\overline{EB}$ assertion in read cycle will occur only when EBC bit in CS5L register is clear.
3. Address becomes valid and $\overline{CS}$ asserts at the start of read access cycle.
4. The external wait input requirement is eliminated when $\overline{CS5}$ is programmed to use internal wait state.

4.4.2.2 WAIT Read Cycle DMA Enabled

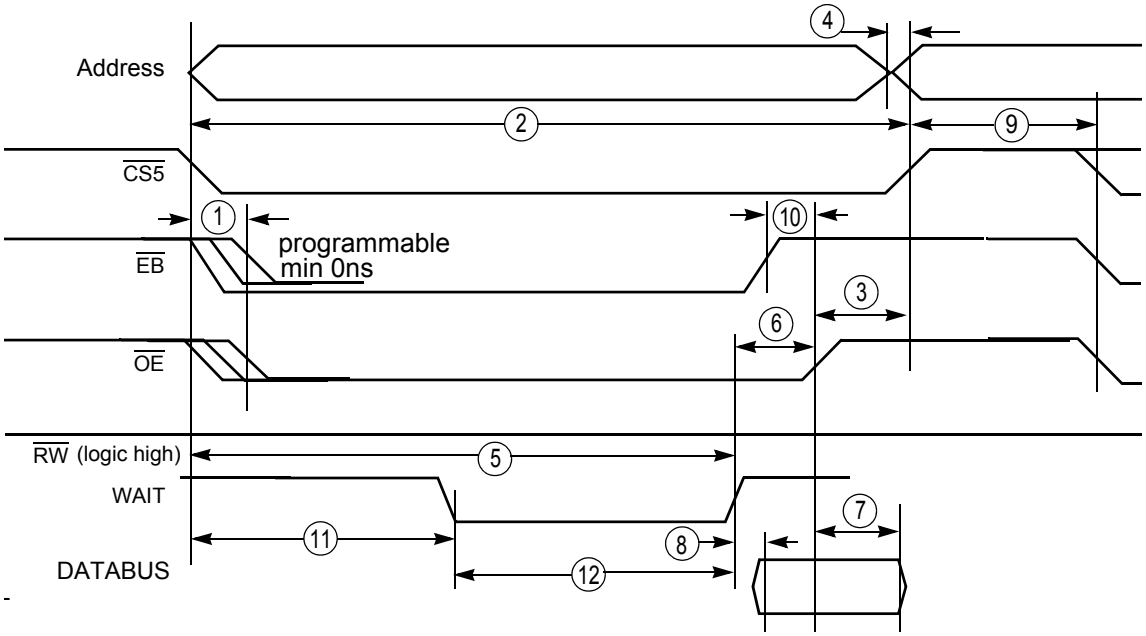
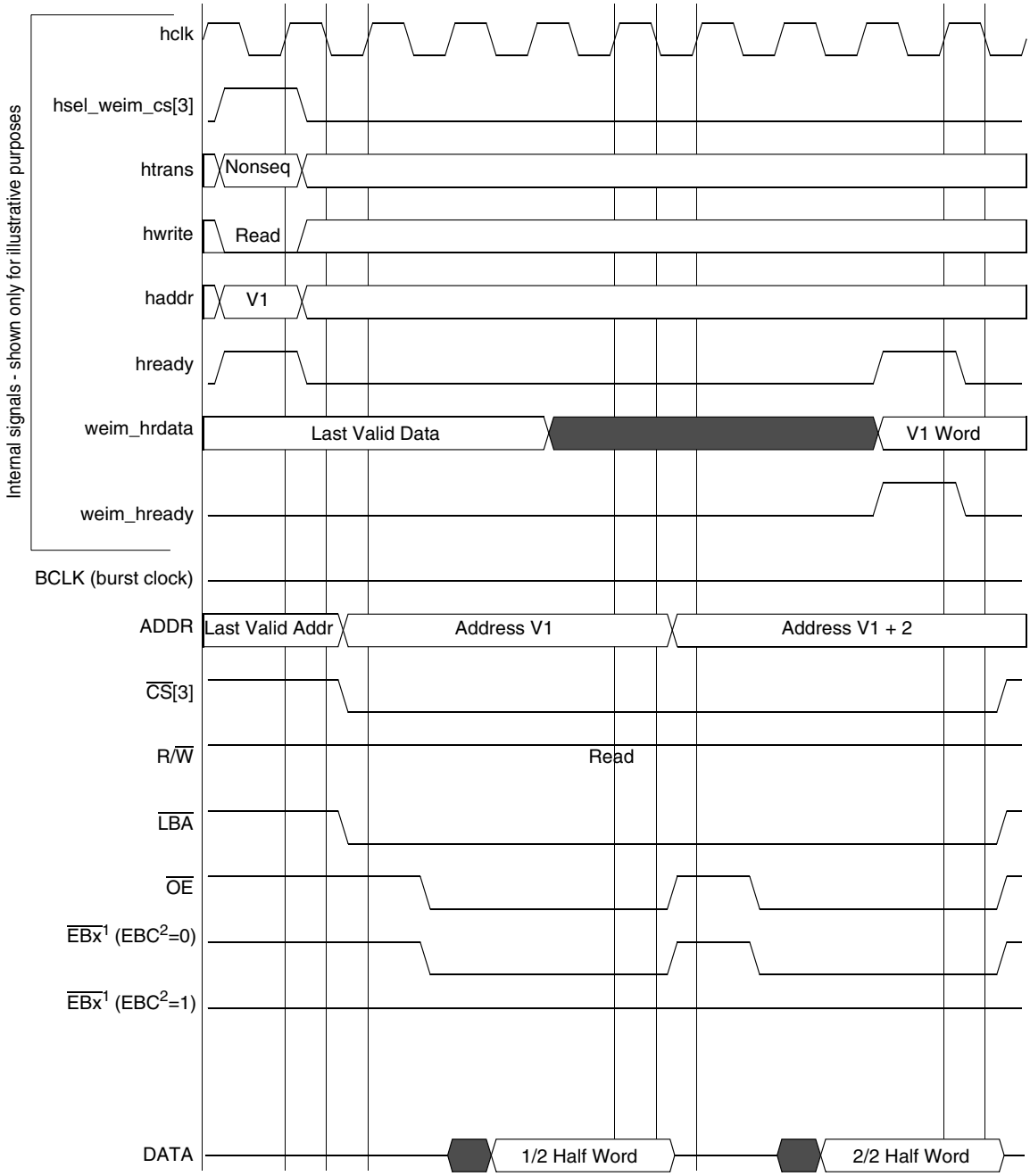


Figure 7. DTACK WAIT Read Cycle DMA Enabled

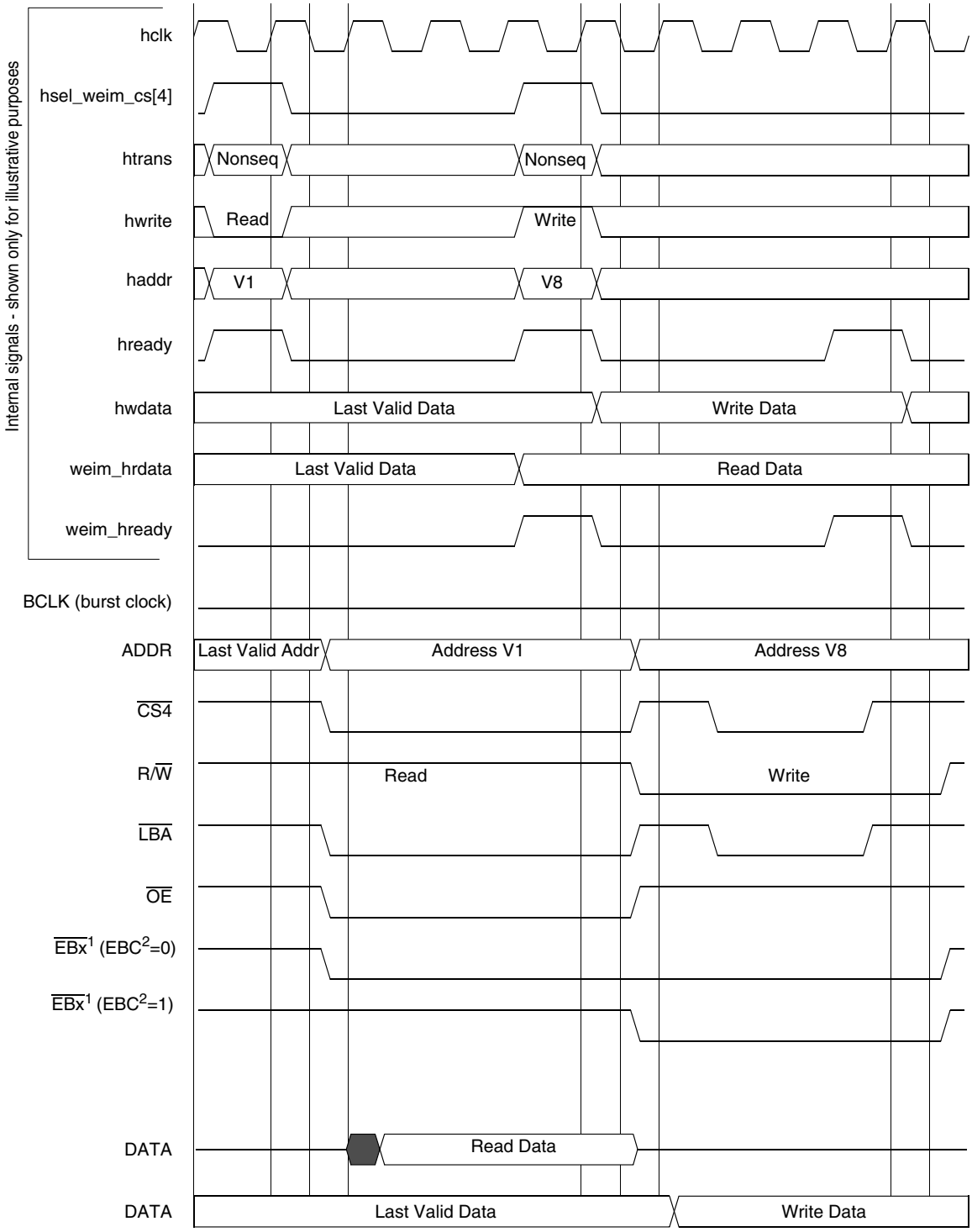
Table 14. DTACK WAIT Read Cycle DMA Enabled: WSC = 111111, DTACK_SEL=1, HCLK=96MHz

Number	Characteristic	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	$\overline{OE}$ and $\overline{EB}$ assertion time	See note 2	–	ns
2	$\overline{CS}$ pulse width	3T	–	ns
3	$\overline{OE}$ negated before $\overline{CS5}$ is negated	1.5T-0.68	1.5T-0.06	ns
4	Address inactived before $\overline{CS}$ negated	–	0.05	ns
5	Wait asserted after $\overline{CS5}$ asserted	–	1020T	ns
6	Wait asserted to $\overline{OE}$ negated	2T+1.57	3T+7.33	ns
7	Data hold timing after $\overline{OE}$ negated	T-1.49	–	ns
8	Data ready after wait is asserted	–	T	ns
9	$\overline{CS}$ deactive to next $\overline{CS}$ active	T	–	ns
10	OE negate after EB negate	0.06	0.18	ns
11	Wait becomes low after CS5 asserted	0	1019T	ns



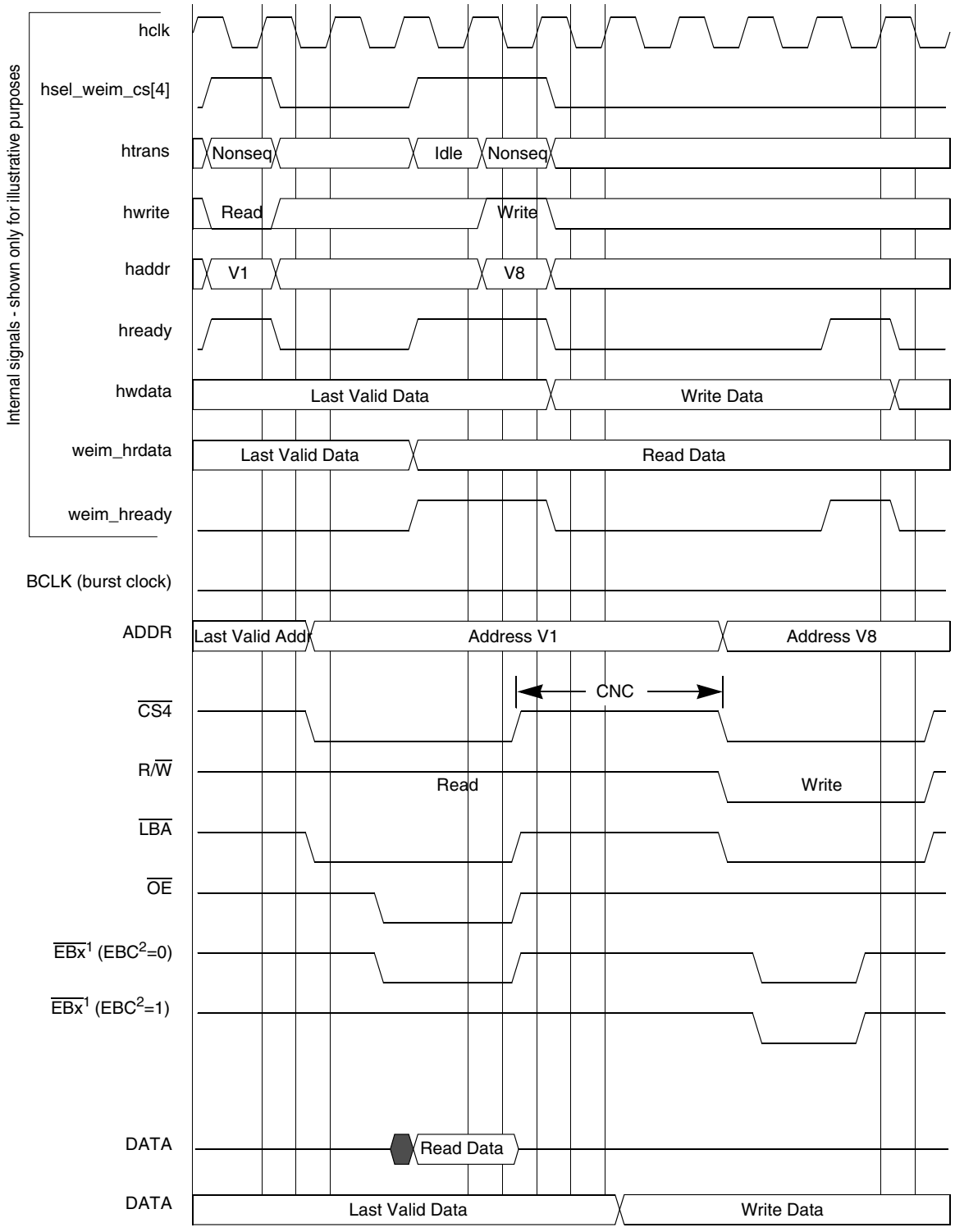
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 14. WSC = 3, OEA = 2, A.WORD/E.HALF



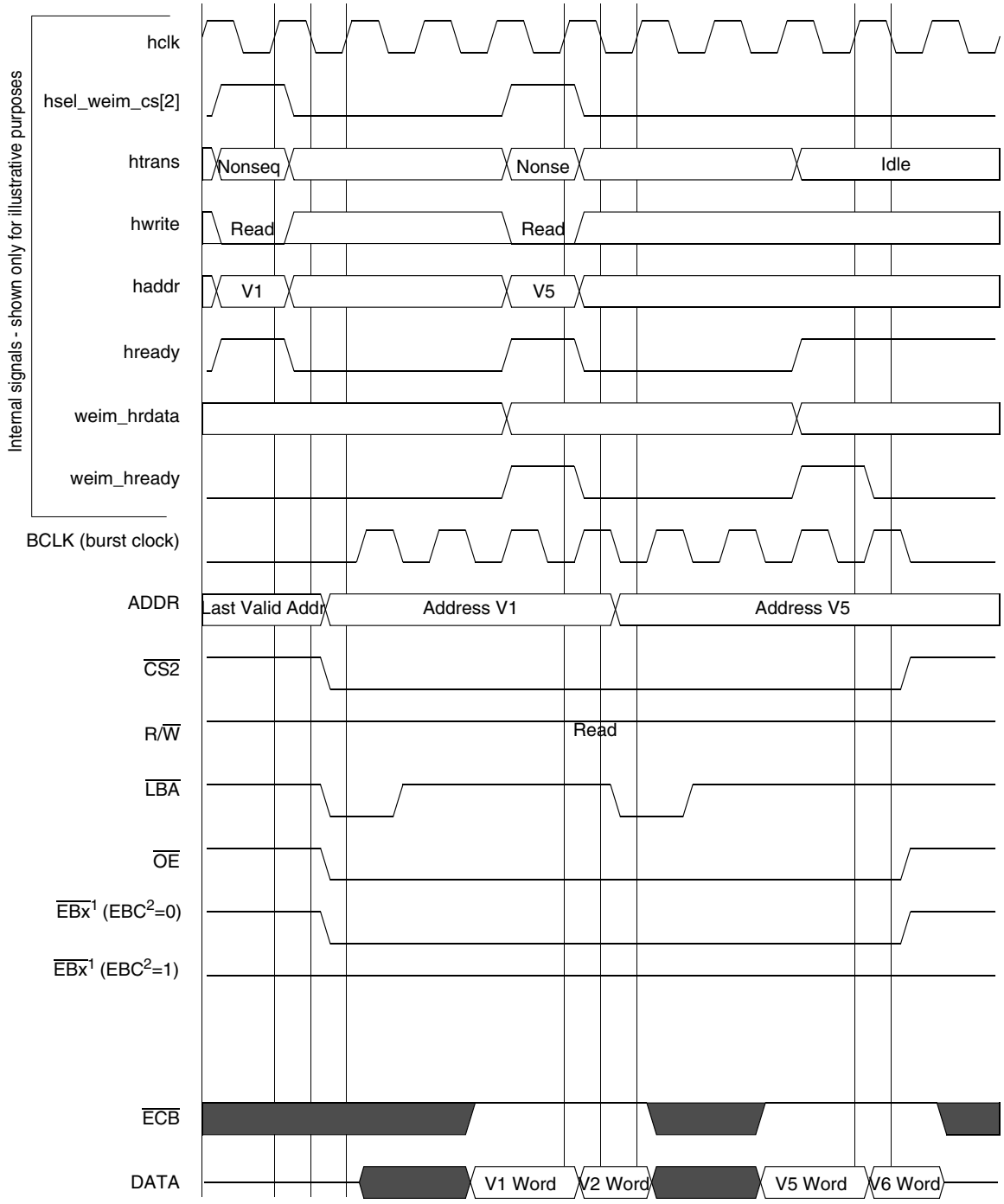
Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 25. WSC = 3, CSA = 1, A.HALF/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 27. WSC = 2, OEA = 2, WEA = 1, WEN = 2, CNC = 3, A.HALF/E.HALF



Note 1: x = 0, 1, 2 or 3
Note 2: EBC = Enable Byte Control bit (bit 11) on the Chip Select Control Register

Figure 28. WSC = 3, SYNC = 1, A.HALF/E.HALF

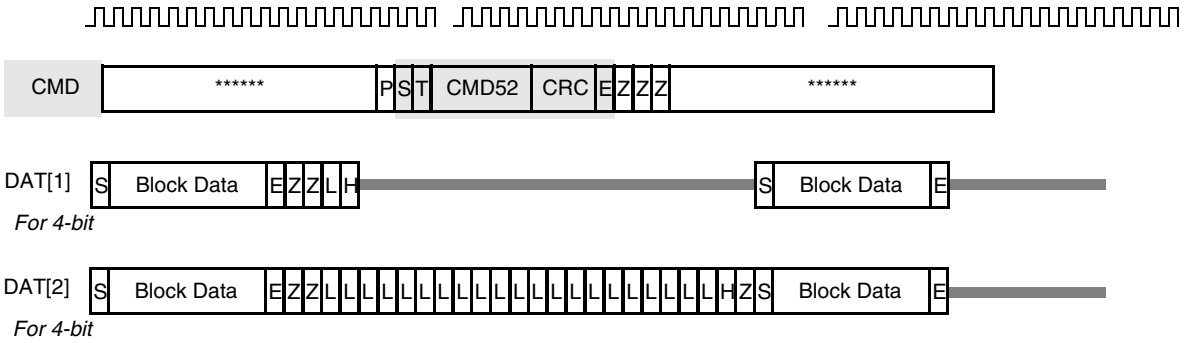


Figure 49. SDIO ReadWait Timing Diagram

4.8 Memory Stick Host Controller

The Memory Stick protocol requires three interface signal line connections for data transfers: MS_BS, MS_SDIO, and MS_SCLKO. Communication is always initiated by the MSHC and operates the bus in either four-state or two-state access mode.

The MS_BS signal classifies data on the SDIO into one of four states (BS0, BS1, BS2, or BS3) according to its attribute and transfer direction. BS0 is the INT transfer state, and during this state no packet transmissions occur. During the BS1, BS2, and BS3 states, packet communications are executed. The BS1, BS2, and BS3 states are regarded as one packet length and one communication transfer is always completed within one packet length (in four-state access mode).

The Memory Stick usually operates in four state access mode and in BS1, BS2, and BS3 bus states. When an error occurs during packet communication, the mode is shifted to two-state access mode, and the BS0 and BS1 bus states are automatically repeated to avoid a bus collision on the SDIO.

Table 25. MSHC Signal Timing Parameter Table (Continued)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
12	MS_SDIO output delay time[1,2]	–	3	ns
13	MS_SDIO input setup time for MS_SCLKO rising edge (RED bit = 0)[3]	18	–	ns
14	MS_SDIO input hold time for MS_SCLKO rising edge (RED bit = 0)[3]	0	–	ns
15	MS_SDIO input setup time for MS_SCLKO falling edge (RED bit = 1)[4]	23	–	ns
16	MS_SDIO input hold time for MS_SCLKO falling edge (RED bit = 1)[4]	0	–	ns

1 Loading capacitor condition is less than or equal to 30pF.

2 An external resistor (100 ~ 200 ohm) should be inserted in series to provide current control on the MS_SDIO pin, because of a possibility of signal conflict between the MS_SDIO pin and Memory Stick SDIO pin when the pin direction changes.

3 If the MSC2[RED] bit = 0, MSHC samples MS_SDIO input data at MS_SCLKO rising edge.

4 If the MSC2[RED] bit = 1, MSHC samples MS_SDIO input data at MS_SCLKO falling edge.

4.9 Pulse-Width Modulator

The PWM can be programmed to select one of two clock signals as its source frequency. The selected clock signal is passed through a divider and a prescaler before being input to the counter. The output is available at the pulse-width modulator output (PWMO) external pin. Its timing diagram is shown in Figure 51 and the parameters are listed in Table 26.

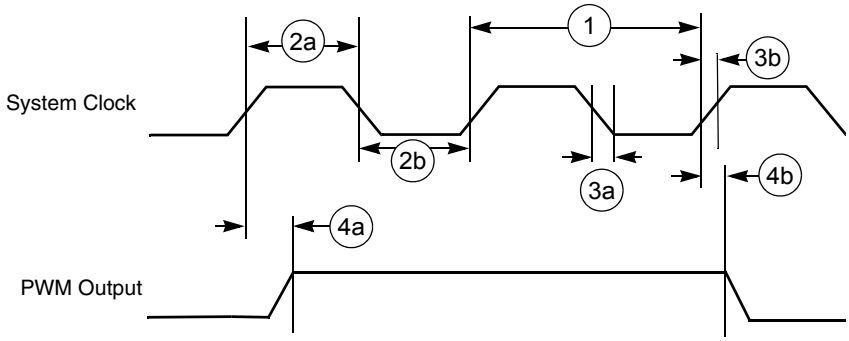


Figure 51. PWM Output Timing Diagram

Table 26. PWM Output Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	System CLK frequency[1]	0	87	0	100	MHz
2a	Clock high time[1]	3.3	–	5/10	–	ns
2b	Clock low time[1]	7.5	–	5/10	–	ns
3a	Clock fall time[1]	–	5	–	5/10	ns

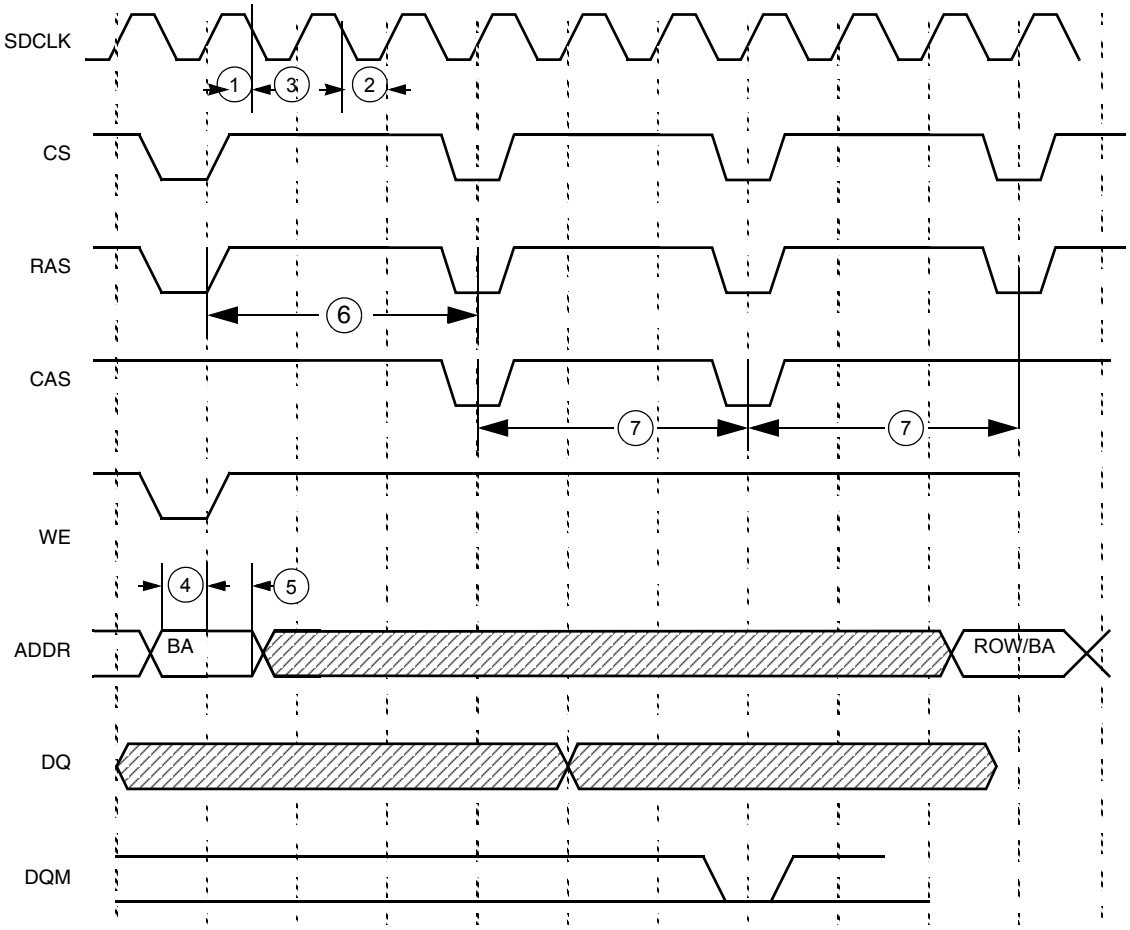


Figure 54. SDRAM Refresh Timing Diagram

Table 29. SDRAM Refresh Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
1	SDRAM clock high-level width	2.67	–	4	–	ns
2	SDRAM clock low-level width	6	–	4	–	ns
3	SDRAM clock cycle time	11.4	–	10	–	ns
4	Address setup time	3.42	–	3	–	ns
5	Address hold time	2.28	–	2	–	ns
6	Precharge cycle period	t_{RP}[1]	–	t_{RP1}	–	ns
7	Auto precharge command period	t_{RC1}	–	t_{RC1}	–	ns

[1] t_{RP} and t_{RC} = SDRAM clock cycle time. These settings can be found in the *MC9328MXL reference manual*.

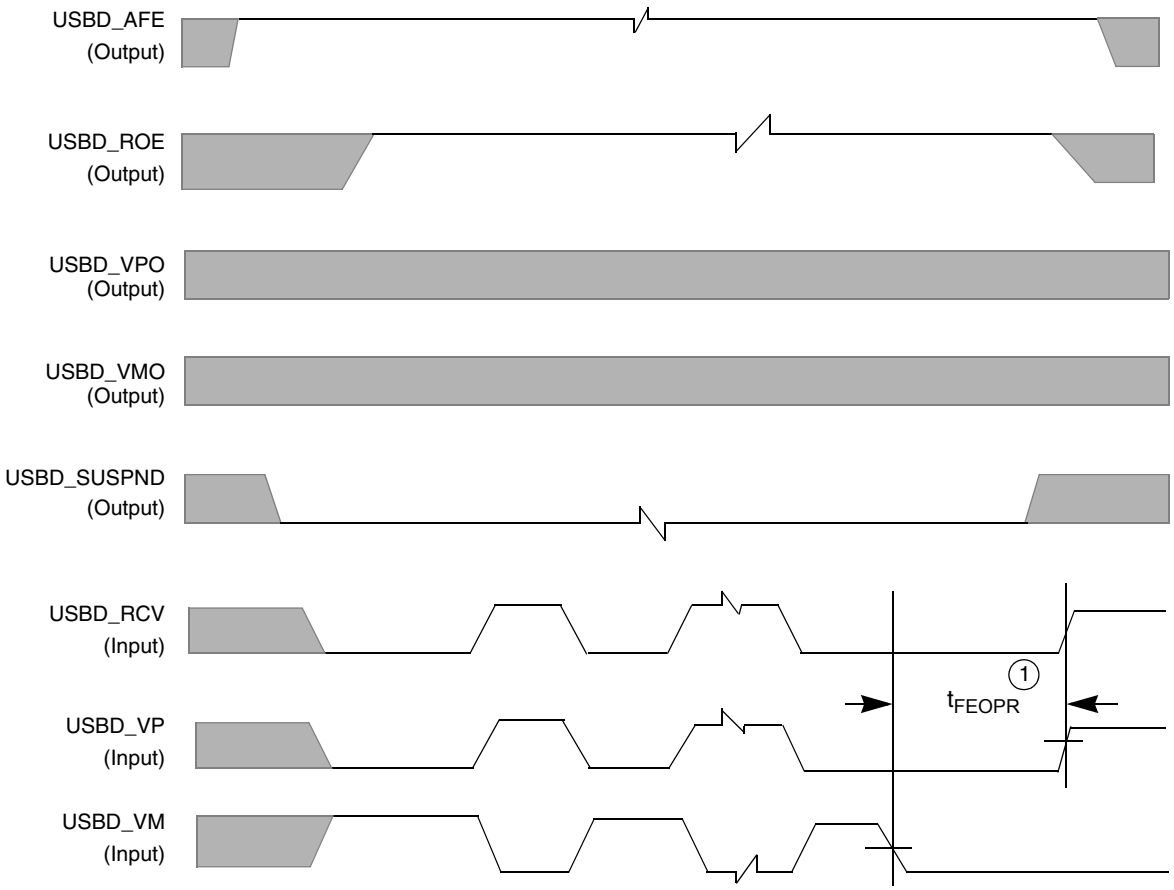


Figure 57. USB Device Timing Diagram for Data Transfer from USB Transceiver (RX)

Table 31. USB Device Timing Parameter Table for Data Transfer from USB Transceiver (RX)

Ref No.	Parameter	3.0 ± 0.3 V		Unit
		Minimum	Maximum	
1	t_{FEOPR}; Receiver SE0 interval of EOP	82	–	ns

4.12 I²C Module

The I²C communication protocol consists of seven elements: START, Data Source/Recipient, Data Direction, Slave Acknowledge, Data, Data Acknowledge, and STOP.

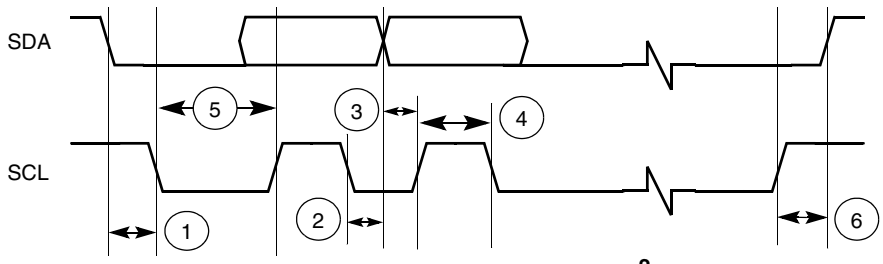


Figure 58. Definition of Bus Timing for I²C

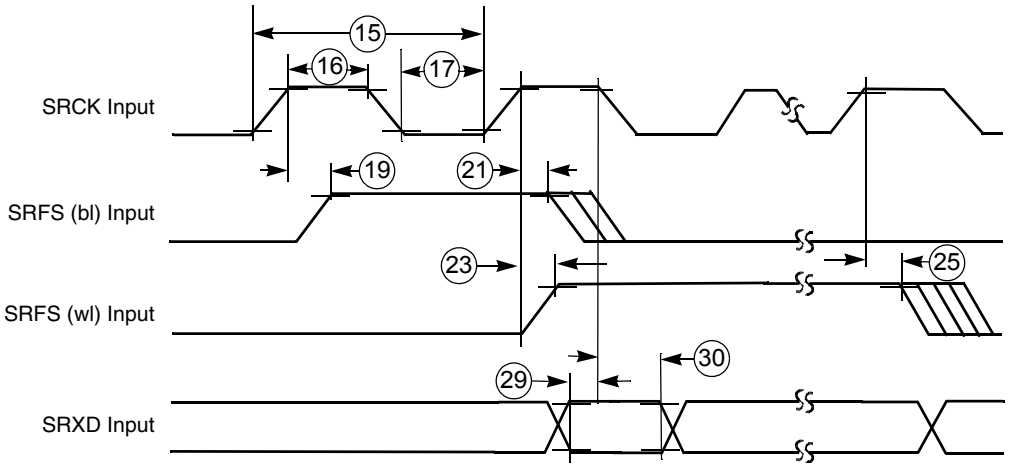


Figure 62. SSI Receiver External Clock Timing Diagram

Table 33. SSI (Port C Primary Function) Timing Parameter Table

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
Internal Clock Operation[1] (Port C Primary Function[2])						
1	STCK/SRCK clock period[1]	95	–	83.3	–	ns
2	STCK high to STFS (bl) high[3]	1.5	4.5	1.3	3.9	ns
3	SRCK high to SRFS (bl) high[3]	-1.2	-1.7	-1.1	-1.5	ns
4	STCK high to STFS (bl) low[3]	2.5	4.3	2.2	3.8	ns
5	SRCK high to SRFS (bl) low[3]	0.1	-0.8	0.1	-0.8	ns
6	STCK high to STFS (wl) high[3]	1.48	4.45	1.3	3.9	ns
7	SRCK high to SRFS (wl) high[3]	-1.1	-1.5	-1.1	-1.5	ns
8	STCK high to STFS (wl) low[3]	2.51	4.33	2.2	3.8	ns
9	SRCK high to SRFS (wl) low[3]	0.1	-0.8	0.1	-0.8	ns
10	STCK high to STXD valid from high impedance	14.25	15.73	12.5	13.8	ns
11a	STCK high to STXD high	0.91	3.08	0.8	2.7	ns
11b	STCK high to STXD low	0.57	3.19	0.5	2.8	ns
12	STCK high to STXD high impedance	12.88	13.57	11.3	11.9	ns
13	SRXD setup time before SRCK low	21.1	–	18.5	–	ns
14	SRXD hold time after SRCK low	0	–	0	–	ns
External Clock Operation (Port C Primary Function[2])						
15	STCK/SRCK clock period[1]	92.8	–	81.4	–	ns
16	STCK/SRCK clock high period	27.1	–	40.7	–	ns
17	STCK/SRCK clock low period	61.1	–	40.7	–	ns

Table 34. SSI (Port B Alternate Function) Timing Parameter Table (Continued)

Ref No.	Parameter	1.8 ± 0.1 V		3.0 ± 0.3 V		Unit
		Minimum	Maximum	Minimum	Maximum	
28	STCK high to STXD high impedance	17.90	29.75	15.7	26.1	ns
29	SRXD setup time before SRCK low	1.14	–	1.0	–	ns
30	SRXD hold time after SRCK low	0	–	0	–	ns
Synchronous Internal Clock Operation (Port B Alternate Function[2])						
31	SRXD setup before STCK falling	18.81	–	16.5	–	ns
32	SRXD hold after STCK falling	0	–	0	–	ns
Synchronous External Clock Operation (Port B Alternate Function[2])						
33	SRXD setup before STCK falling	1.14	–	1.0	–	ns
34	SRXD hold after STCK falling	0	–	0	–	ns

1 All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal STCK/SRCK and/or the frame sync STFS/SRFS shown in the tables and in the figures.

2 There are 2 set of I/O signals for the SSI module. They are from Port C primary function (pad 257 to pad 261) and Port B alternate function (pad 283 to pad 288). When SSI signals are configured as outputs, they can be viewed both at Port C primary function and Port B alternate function. When SSI signals are configured as inputs, the SSI module selects the input based on FMCR register bits in the Clock controller module (CRM). By default, the input are selected from Port C primary function.

3 bl = bit length; wl = word length.

4.14 CMOS Sensor Interface

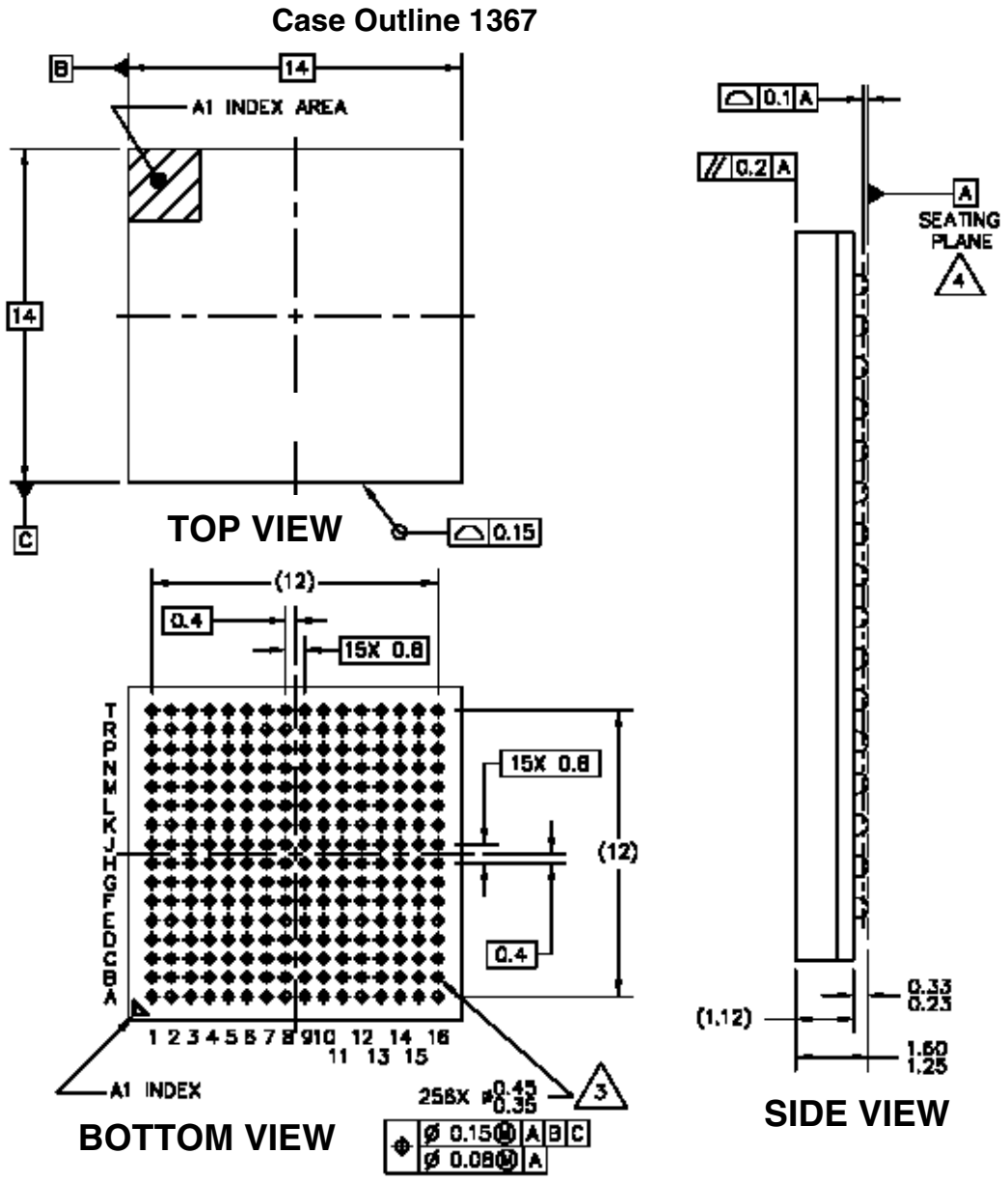
The CMOS Sensor Interface (CSI) module consists of a control register to configure the interface timing, a control register for statistic data generation, a status register, interface logic, a 32 × 32 image data receive FIFO, and a 16 × 32 statistic data FIFO.

4.14.1 Gated Clock Mode

Figure 63 shows the timing diagram when the CMOS sensor output data is configured for negative edge and the CSI is programmed to received data on the positive edge. Figure 64 shows the timing diagram when the CMOS sensor output data is configured for positive edge and the CSI is programmed to received data in negative edge. The parameters for the timing diagrams are listed in Table 35.

5.1 MAPBGA 256 Package Dimensions

Figure 67 illustrates the 256 MAPBGA 14 mm × 14 mm × 1.30 mm package, with an 0.8 mm pad pitch. The device designator for the MAPBGA package is VH.



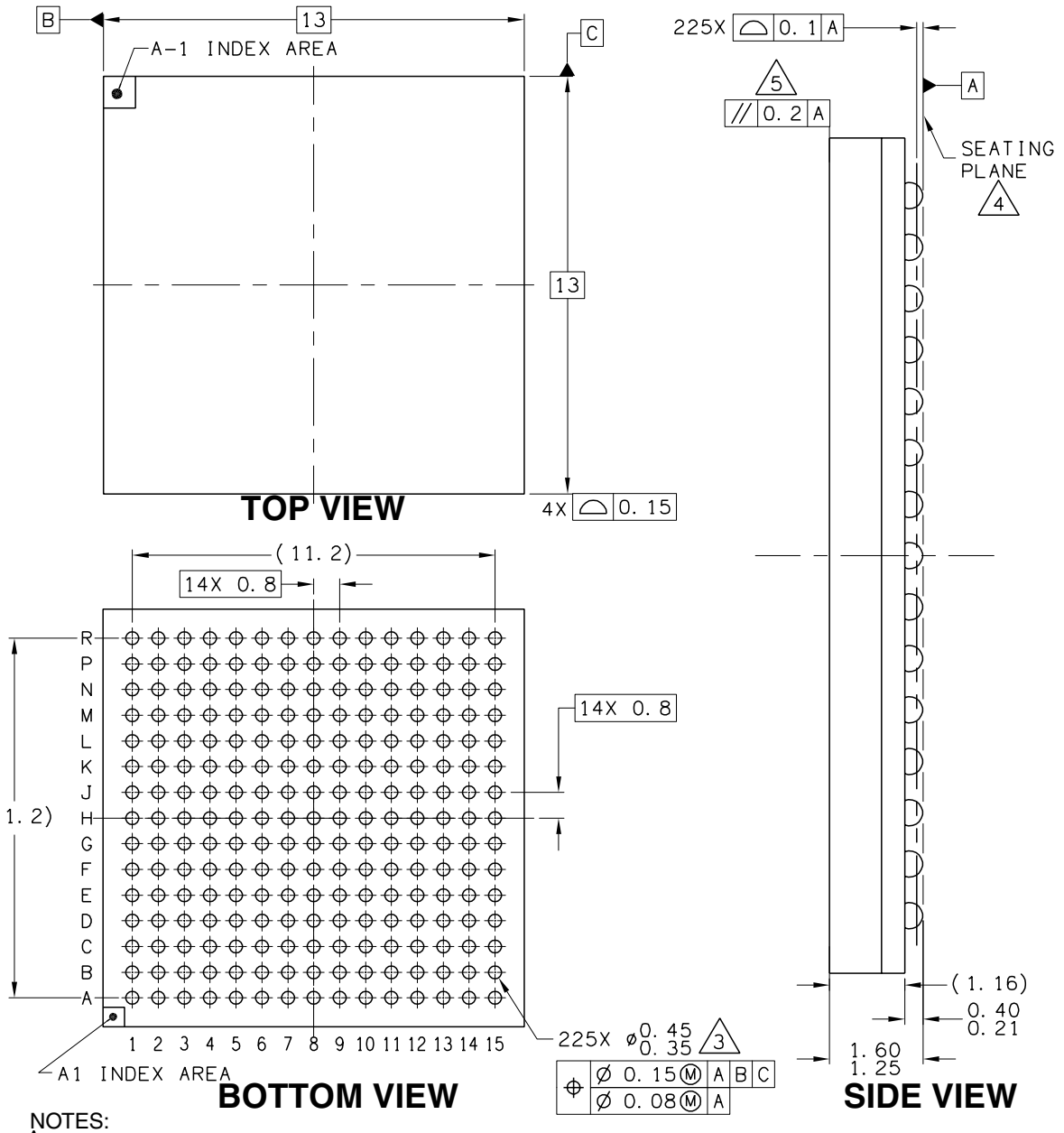
NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2.INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14 5M-1994.
3.MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE IS DEFINED BY SPHERICAL CROWNS OF THE SOLDER BALLS.

Figure 67. i.MXL 256 MAPBGA Mechanical Drawing

5.2 MAPBGA 225 Package Dimensions

Figure 68 illustrates the 225 MAPBGA 13 mm × 13 mm package.

Case Outline 1304B



NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES PER ASME Y14 5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE IS DEFINED BY SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

Figure 68. i.MXL 225 MAPBGA Mechanical Drawing

How to Reach Us:

Home Page:
www.freescale.com

E-mail:
support@freescale.com

USA/Europe or Locations Not Listed:
Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064, Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:
Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

***For Literature Requests Only*:**
Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-521-6274 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. “Typical” parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including “Typicals”, must be validated for each customer application by customer’s technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. ARM and the ARM POWERED logo are the registered trademarks of ARM Limited. ARM9, ARM920T, and ARM9TDMI are the trademarks of ARM Limited. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2006. All rights reserved.

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see http://www.freescale.com or contact your Freescale sales representative.

For information on Freescale’s Environmental Products program, go to http://www.freescale.com/epp.

Document Number: MC9328MXL
Rev. 8
12/2006